

NCV4274, NCV4274A

Regulator Family, 400 mA, 2% and 4% Voltage

Description

The NCV4274 and NCV4274A is a precision micro-power voltage regulator with an output current capability of 400 mA available in the DPAK, D2PAK and SOT-223 packages.

The output voltage is accurate within $\pm 2.0\%$ or $\pm 4.0\%$ depending on the version with a maximum dropout voltage of 0.5 V with an input up to 40 V. Low quiescent current is a feature drawing only 150 μA with a 1 mA load. This part is ideal for automotive and all battery operated microprocessor equipment.

The regulator is protected against reverse battery, short circuit, and thermal overload conditions. The device can withstand load dump transients making it suitable for use in automotive environments.

Features

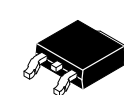
- 2.5, 3.3 V, 5.0 V, 8.5 V, $\pm 2.0\%$ Output Options
- 2.5, 3.3 V, 5.0 V, $\pm 4.0\%$ Output Options
- Low 150 μA Quiescent Current at 1 mA load current
- 400 mA Output Current Capability
- Fault Protection
 - -42 V Reverse Voltage
 - Short Circuit
 - Thermal Overload
- Very Low Dropout Voltage
- NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These are Pb-Free Devices



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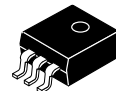
MARKING DIAGRAMS



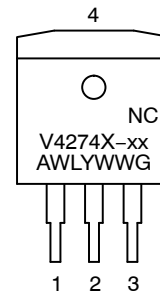
DPAK
DT SUFFIX
CASE 369C



1 Input
2, 4 Ground
3 Output



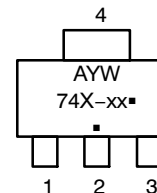
D2PAK
DS SUFFIX
CASE 418AF



1 Input
2, 4 Ground
3 Output



SOT-223
ST SUFFIX
CASE 318E



1 Input
2, 4 Ground
3 Output

X = A or blank
xx = Voltage Ratings
A = Assembly Location
L, WL = Wafer Lot
Y = Year
WW, W = Work Week
G, ■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 15 of this data sheet.

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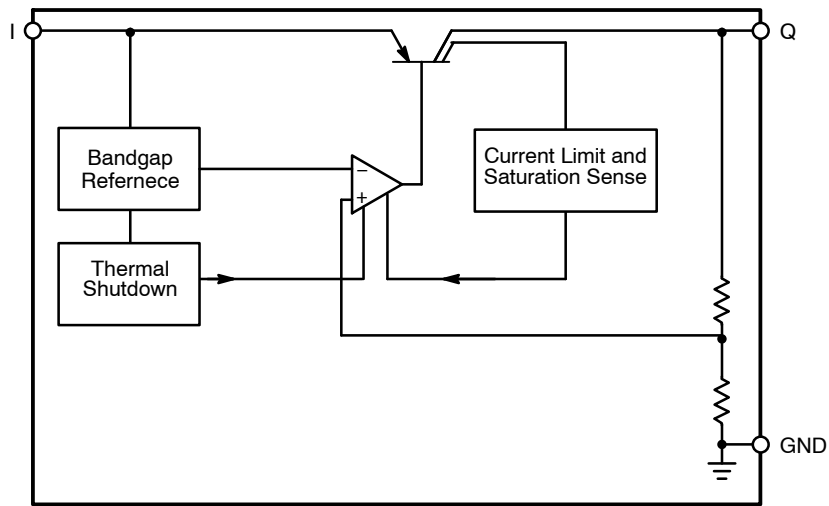


Figure 1. Block Diagram

Pin Definitions and Functions

| Pin No. | Symbol | Function |
|---------|--------|--|
| 1 | I | Input; Bypass directly at the IC a ceramic capacitor to GND. |
| 2,4 | GND | Ground |
| 3 | Q | Output; Bypass with a capacitor to GND. |

1. DPAK 3LD package code 6025
2. D2PAK 3LD package code 6083

ABSOLUTE MAXIMUM RATINGS

| Pin Symbol, Parameter | | Symbol | Condition | Min | Max | Unit |
|--|---------|-------------|-------------|--------------------|--------------------|------|
| I, Input-to-Regulator | Voltage | V_I | | -42 | 45 | V |
| | Current | I_I | | Internally Limited | Internally Limited | |
| I, Input peak Transient Voltage to Regulator with Respect to GND | | V_I | | | 60 | V |
| Q, Regulated Output | Voltage | V_Q | $V_Q = V_I$ | -1.0 | 40 | V |
| | Current | I_Q | | Internally Limited | Internally Limited | |
| GND, Ground Current | | I_{GND} | | - | 100 | mA |
| Junction Temperature | | T_J | | - | 150 | °C |
| Storage Temperature | | T_{Stg} | | -50 | 150 | °C |
| ESD Capability, Human Body Model | | ESD_{HB} | | 4 | | kV |
| ESD Capability, Machine Model | | ESD_{MM} | | 200 | | V |
| ESD Capability, Charged Device Model | | ESD_{CDM} | | 1 | | kV |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

3. This device series incorporates ESD protection and is tested by the following methods:
 ESD HBM tested per AEC-Q100-002 (EIA/JESD22-A114)
 ESD MM tested per AEC-Q100-003 (EIA/JESD22-A115)
 ESD CDM tested per EIA/JES D22/C101, Field Induced Charge Model

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OPERATING RANGE

| Parameter | Symbol | Condition | Min | Max | Unit |
|--|--------|-----------|-----|-----|------|
| Input Voltage (8.5 V Version) | V_I | | 9.0 | 40 | V |
| Input Voltage (5.0 V Version) | V_I | | 5.5 | 40 | V |
| Input Voltage (3.3 V, and 2.5 V Version) | V_I | | 4.5 | 40 | V |
| Junction Temperature | T_J | | -40 | 150 | °C |

THERMAL RESISTANCE

| Parameter | Symbol | Condition | Min | Max | Unit |
|---------------------|--|-----------|-----|-------------------|------|
| Junction-to-Ambient | DPAK R_{thja} | | - | 70 (Note 4) | °C/W |
| Junction-to-Ambient | D2PAK R_{thja} | | - | 60 (Note 4) | °C/W |
| Junction-to-Case | DPAK R_{thjc} | | - | 4 | °C/W |
| Junction-to-Case | D2PAK R_{thjc} | | - | 3 | °C/W |
| Junction-to-Tab | SOT-223 Ψ_{JLX} , Ψ_{LX} | | - | 14.5 (Note 5) | °C/W |
| Junction-to-Ambient | SOT-223 $R_{\theta JA}$, θ_{JA} | | - | 169.7 (Note 5) | °C/W |

4. Soldered in, minimal footprint, FR4
 5. 1 oz copper, 5 mm² copper area, FR4

LEAD FREE SOLDERING TEMPERATURE AND MSL

| Parameter | Symbol | Condition | Min | Max | Unit |
|---|-----------|--|--------|--------|------|
| Lead Free Soldering, (Note 6) Reflow (SMD styles only), Pb-Free | T_{sld} | 60s – 150s Above 217s 40s Max at Peak | - | 265 pk | °C |
| Moisture Sensitivity Level | MSL | DPAK and D2PAK SOT-223 | 1 3 | - - | |

6. Per IPC/JEDEC J-STD-020C

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ELECTRICAL CHARACTERISTICS

-40°C < T_J < 150°C; V_I = 13.5 V unless otherwise noted.

| Parameter | Symbol | Test Conditions | Min | Typ | Max | Min | Typ | Max | Unit |
|----------------------------------|---------------------|---|----------|-----|------|---------|-----|------|------|
| | | | NCV4274A | | | NCV4274 | | | |
| REGULATOR | | | | | | | | | |
| Output Voltage (8.5 V Version) | V _Q | 5 mA < I _Q < 200 mA 9.5 V < V _I < 40 V | 8.33 | 8.5 | 8.67 | - | - | - | V |
| Output Voltage (8.5 V Version) | V _Q | 5 mA < I _Q < 400 mA 9.5 V < V _I < 28 V | 8.33 | 8.5 | 8.67 | - | - | - | V |
| Output Voltage (5.0 V Version) | V _Q | 5 mA < I _Q < 400 mA 6 V < V _I < 28 V | 4.9 | 5.0 | 5.1 | 4.8 | 5.0 | 5.2 | V |
| Output Voltage (5.0 V Version) | V _Q | 5 mA < I _Q < 200 mA 6 V < V _I < 40 V | 4.9 | 5.0 | 5.1 | 4.8 | 5.0 | 5.2 | V |
| Output Voltage (3.3 V Version) | V _Q | 5 mA < I _Q < 400 mA 4.5 V < V _I < 28 V | 3.23 | 3.3 | 3.37 | 3.17 | 3.3 | 3.43 | V |
| Output Voltage (3.3 V Version) | V _Q | 5 mA < I _Q < 200 mA 4.5 V < V _I < 40 V | 3.23 | 3.3 | 3.37 | 3.17 | 3.3 | 3.43 | V |
| Output Voltage (2.5 V Version) | V _Q | 5 mA < I _Q < 400 mA 4.5 V < V _I < 28 V | 2.45 | 2.5 | 2.55 | 2.4 | 2.5 | 2.6 | V |
| Output Voltage (2.5 V Version) | V _Q | 5 mA < I _Q < 200 mA 4.5 V < V _I < 40 V | 2.45 | 2.5 | 2.55 | 2.4 | 2.5 | 2.6 | V |
| Current Limit | I _Q | - | 400 | 600 | - | 400 | 600 | - | mA |
| Quiescent Current | I _q | I _Q = 1 mA V _Q = 8.5 V V _Q = 5.0 V V _Q = 3.3 V V _Q = 2.5 V I _Q = 250 mA V _Q = 8.5 V V _Q = 5.0 V V _Q = 3.3 V V _Q = 2.5 V I _Q = 400 mA V _Q = 8.5 V V _Q = 5.0 V V _Q = 3.3 V V _Q = 2.5 V | - | 195 | 250 | - | - | - | μA |
| | | | - | 190 | 250 | - | 190 | 250 | μA |
| | | | - | 145 | 250 | - | 145 | 250 | μA |
| | | | - | 140 | 250 | - | 140 | 250 | μA |
| | | | - | 10 | 15 | - | - | - | mA |
| | | | - | 10 | 15 | - | 10 | 15 | mA |
| | | | - | 13 | 20 | - | 13 | 20 | mA |
| | | | - | 12 | 20 | - | 12 | 20 | mA |
| | | | - | 20 | 35 | - | - | - | mA |
| | | | - | 20 | 35 | - | 20 | 35 | mA |
| | | | - | 30 | 45 | - | 30 | 45 | mA |
| | | | - | 28 | 45 | - | 28 | 45 | mA |
| Dropout Voltage | V _{DR} | I _Q = 250 mA, V _{DR} = V _I - V _Q | | | | | | | |
| 8.5 V Version | | V _I = 8.5 V | - | 250 | 500 | - | - | - | mV |
| 5.0 V Version | | V _I = 5.0 V | - | 250 | 500 | - | 250 | 500 | mV |
| 3.3 V Version | | V _I = 4.5 V | - | - | 1.27 | - | - | 1.33 | V |
| 2.5 V Version | | V _I = 4.5 V | - | - | 2.05 | - | - | 2.1 | V |
| Load Regulation | ΔV _Q | I _Q = 5 mA to 400 mA | - | 7 | 20 | - | 7 | 30 | mV |
| Line Regulation | ΔV _Q | ΔV _I = 12 V to 32 V I _Q = 5 mA | - | 10 | 25 | - | 10 | 25 | mV |
| Power Supply Ripple Rejection | P _{SRR} | f _r = 100 Hz, V _r = 0.5 V _{PP} | - | 60 | - | - | 60 | - | dB |
| Temperature output voltage drift | ΔV _Q /ΔT | | - | 0.5 | - | - | 0.5 | - | mV/K |
| Thermal Shutdown Temperature* | T _{SD} | I _Q = 5 mA | 165 | - | 210 | 165 | - | 210 | °C |

*Guaranteed by design, not tested in production

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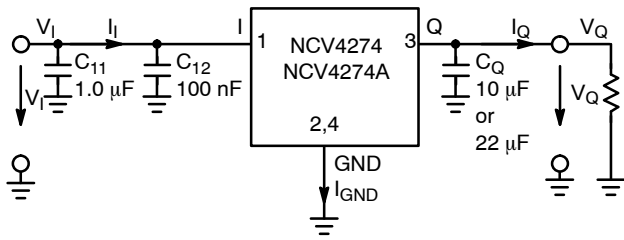


Figure 2. Measuring Circuit

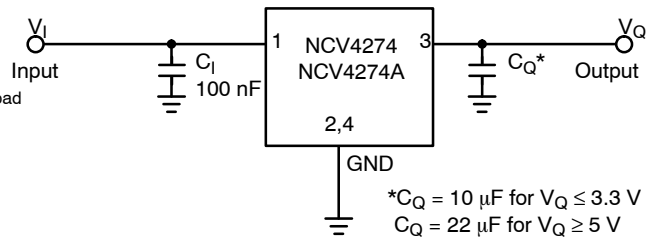


Figure 3. Application Circuit

TYPICAL CHARACTERISTIC CURVES

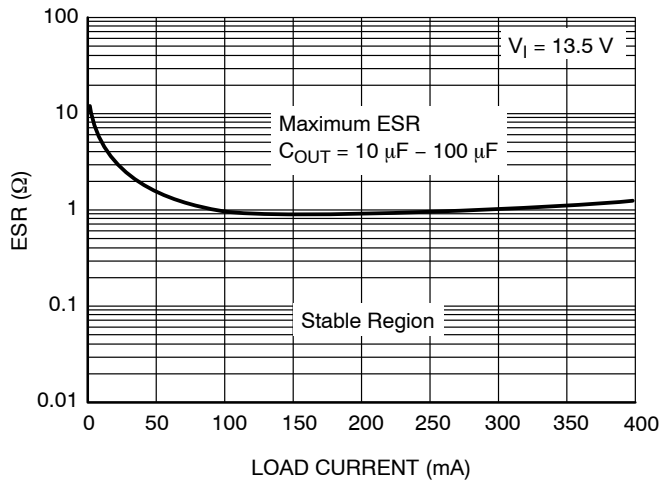


Figure 4. ESR Characterization – 3.3 V, 5 V and 8.5 V Versions

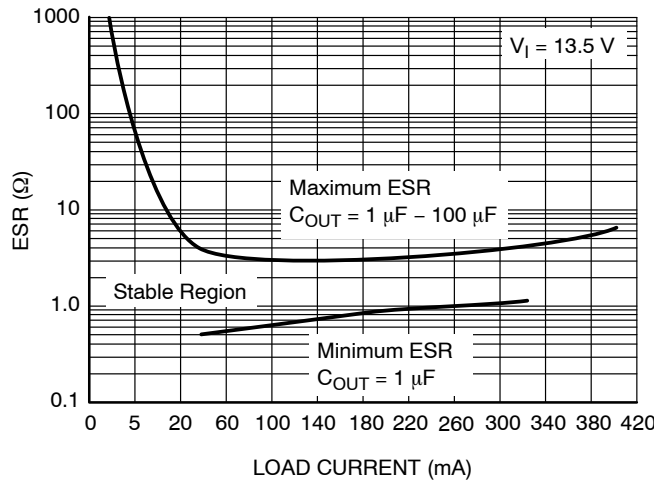


Figure 5. ESR Characterization – 2.5 V Version

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TYPICAL CHARACTERISTIC CURVES – 8.5 V Version

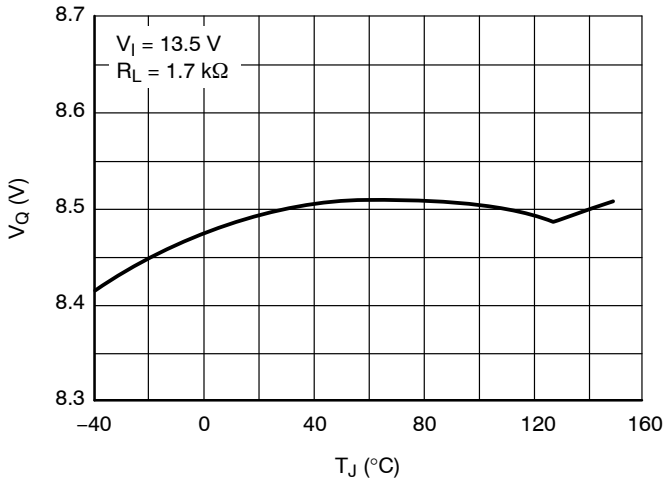


Figure 6. Output Voltage vs. Junction Temperature

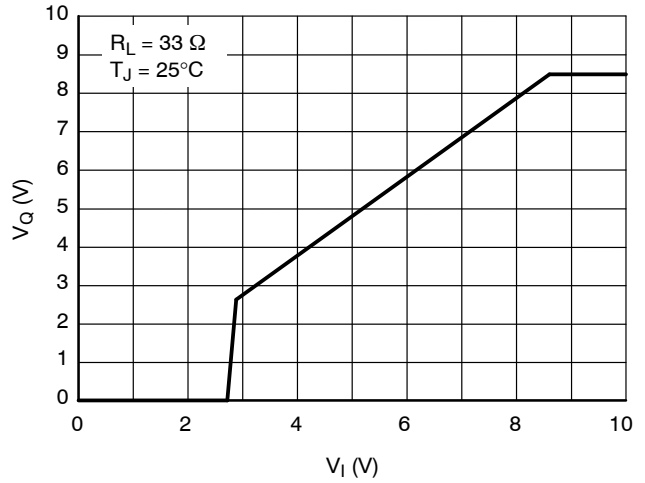


Figure 7. Output Voltage vs. Input Voltage

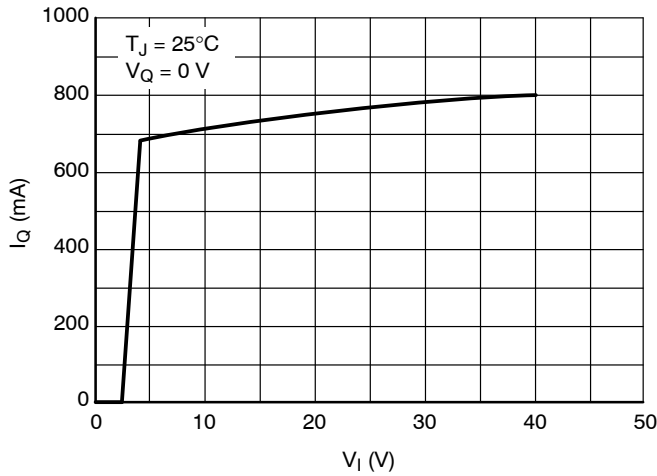


Figure 8. Output Current vs. Input Voltage

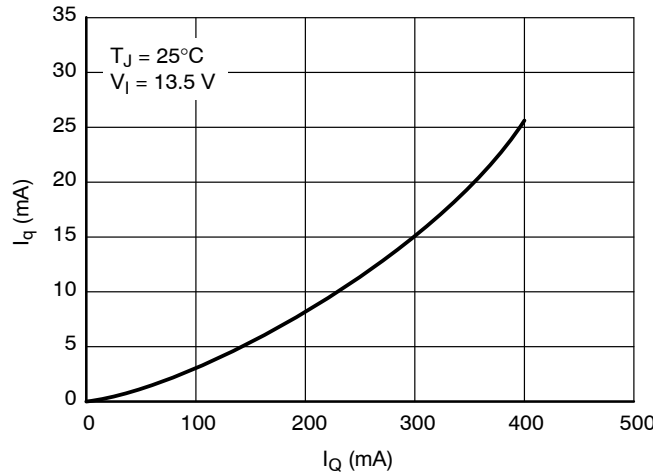


Figure 9. Current Consumption vs. Output Current (High Load)

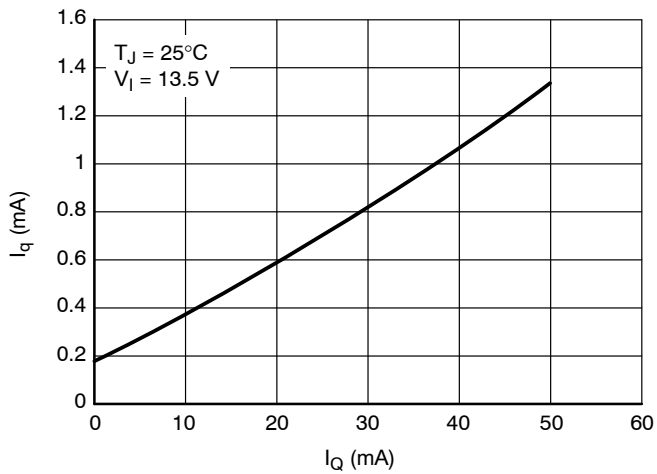


Figure 10. Current Consumption vs. Output Current (Low Load)

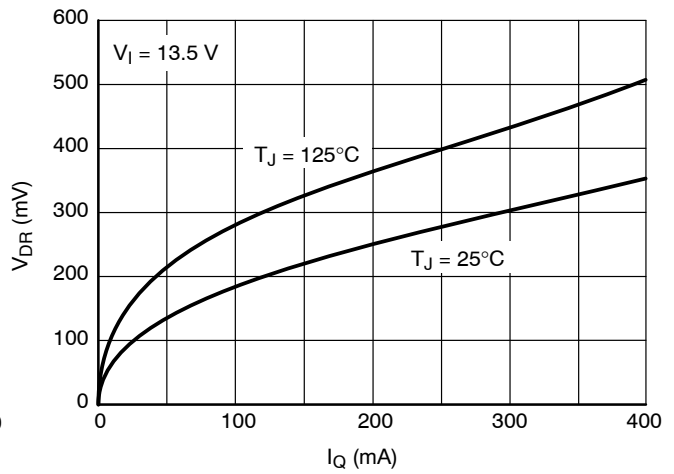


Figure 11. Drop Voltage vs. Output Current

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TYPICAL CHARACTERISTIC CURVES – 8.5 V Version

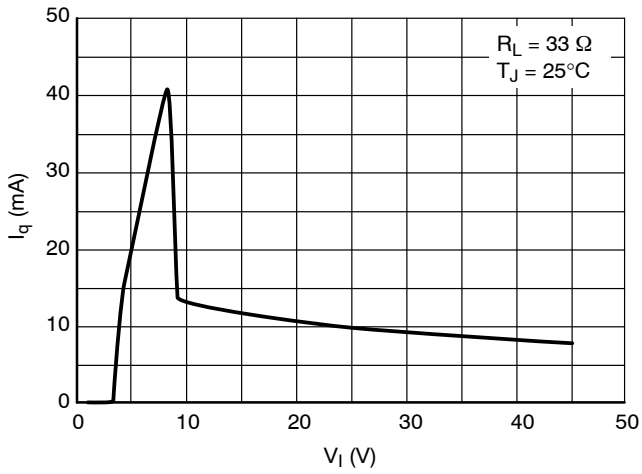


Figure 12. Current Consumption vs. Input Voltage

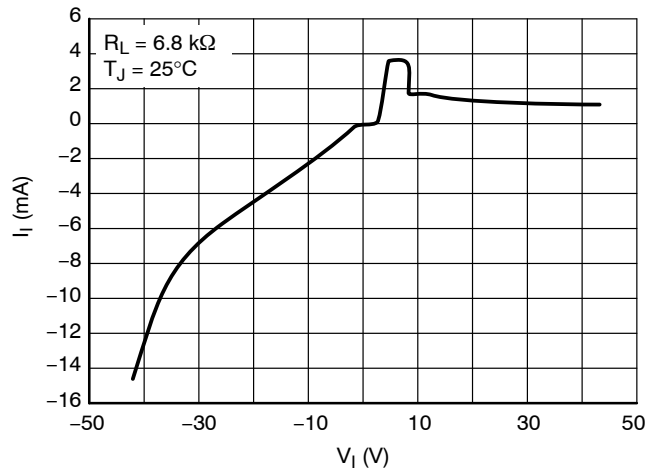


Figure 13. Input Current vs. Input Voltage

TYPICAL CHARACTERISTIC CURVES – 5.0 V Version

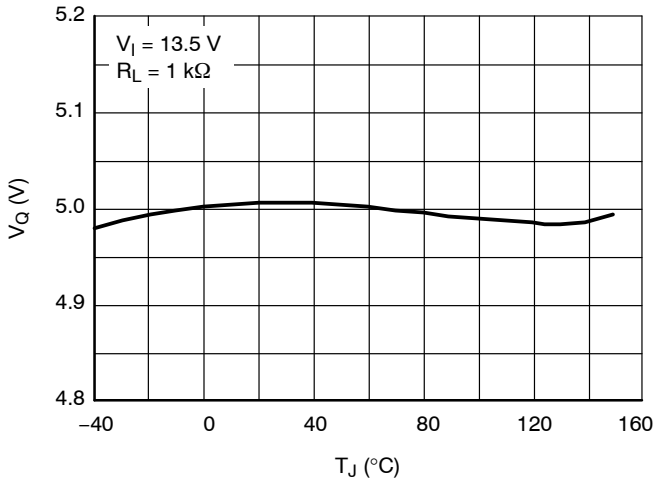


Figure 14. Output Voltage vs. Junction Temperature

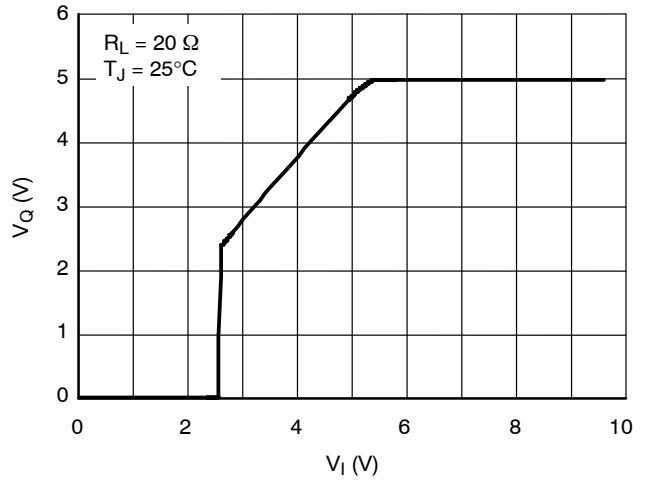


Figure 15. Output Voltage vs. Input Voltage

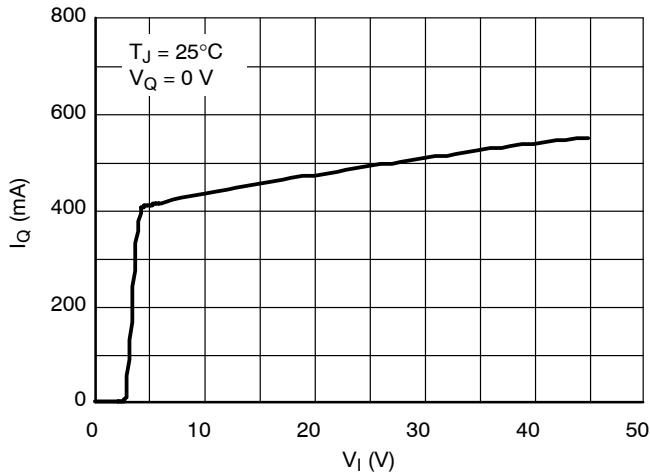


Figure 16. Output Current vs. Input Voltage

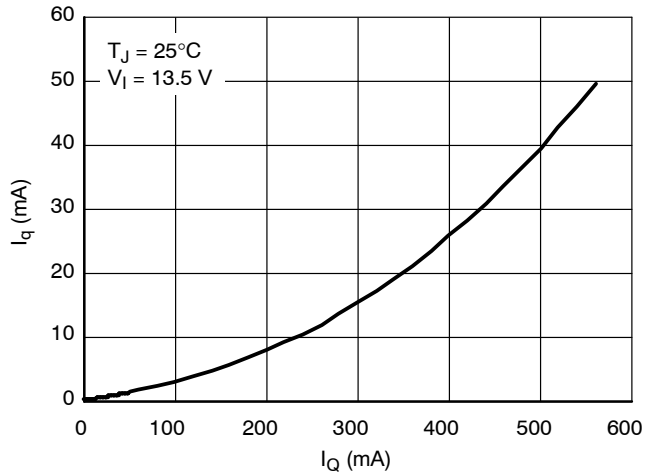


Figure 17. Current Consumption vs. Output Current (High Load)

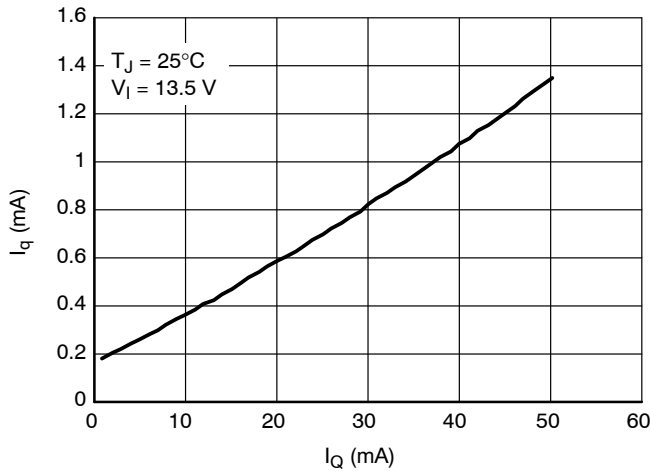


Figure 18. Current Consumption vs. Output Current (Low Load)

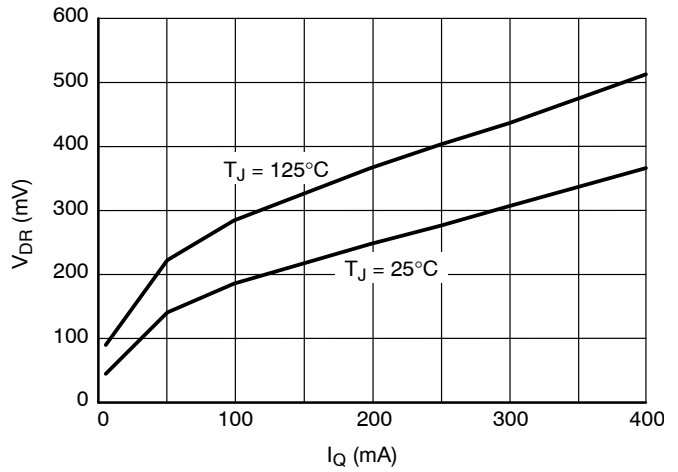


Figure 19. Drop Voltage vs. Output Current

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TYPICAL CHARACTERISTIC CURVES – 5.0 V Version

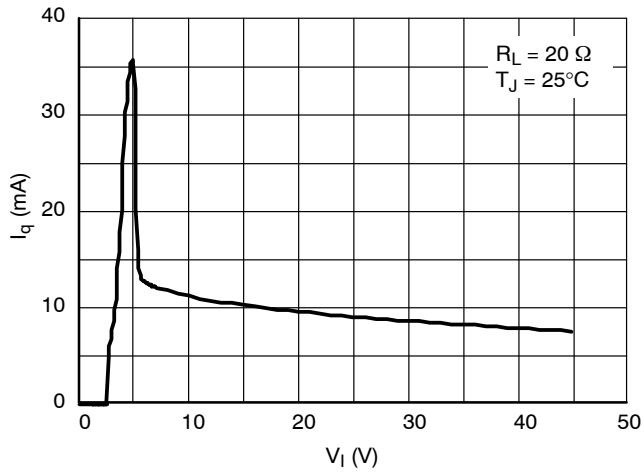


Figure 20. Current Consumption vs. Input Voltage

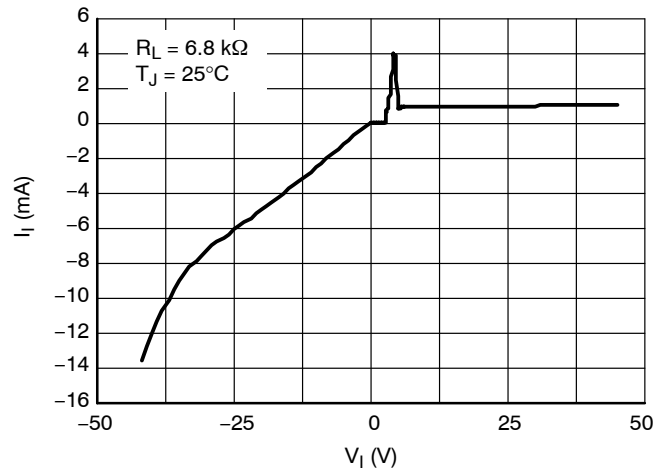


Figure 21. Input Current vs. Input Voltage

TYPICAL CHARACTERISTIC CURVES – 3.3 V Version

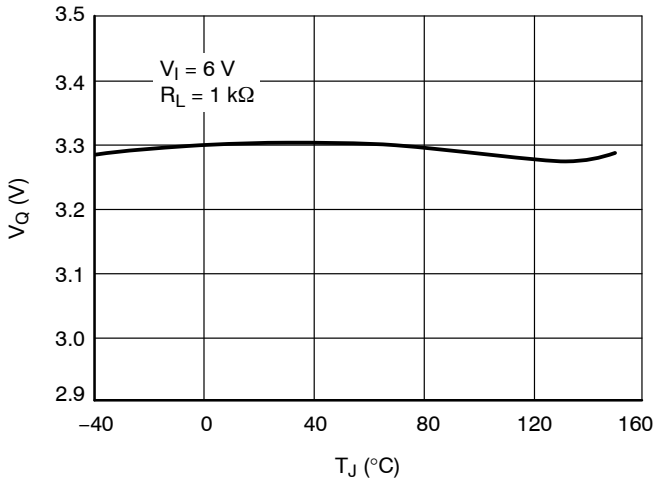


Figure 22. Output Voltage vs. Junction Temperature

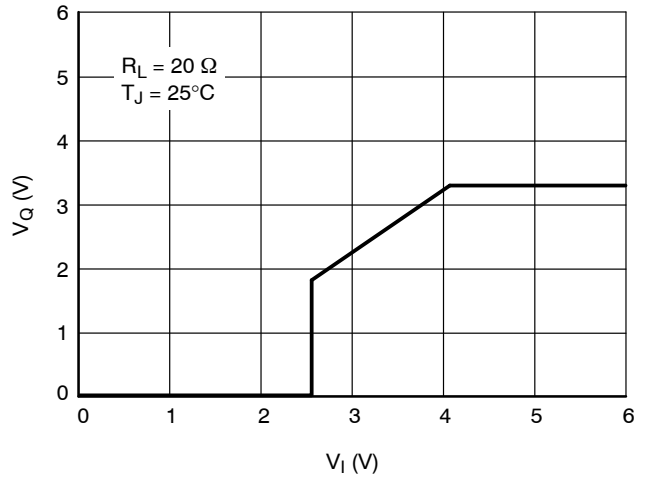


Figure 23. Output Voltage vs. Input Voltage

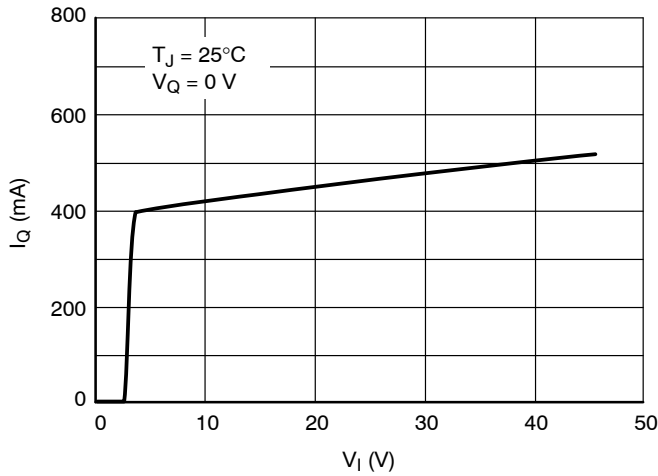


Figure 24. Output Current vs. Input Voltage

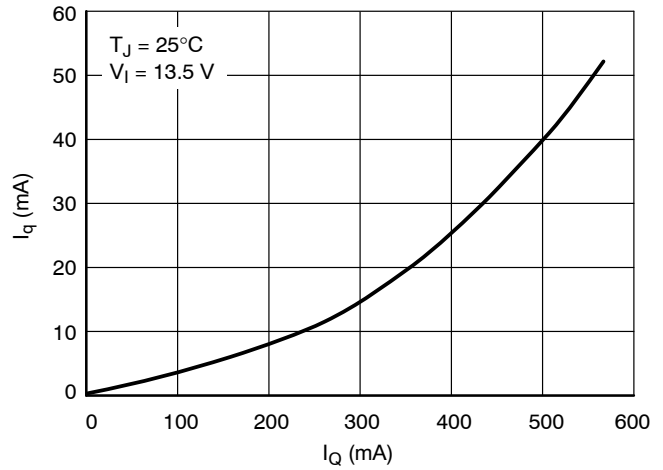


Figure 25. Current Consumption vs. Output Current (High Load)

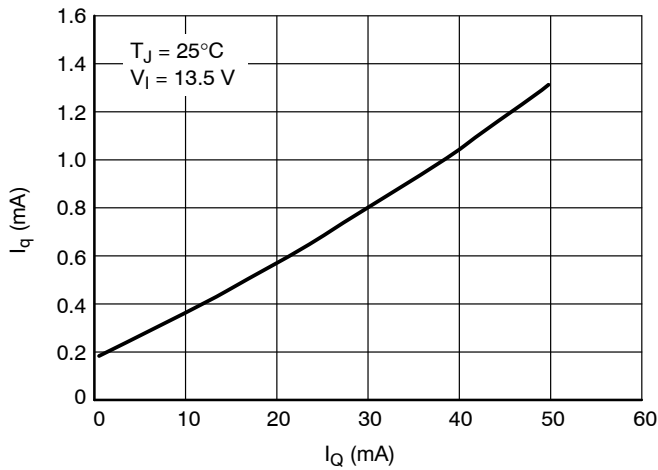


Figure 26. Current Consumption vs. Output Current (Low Load)

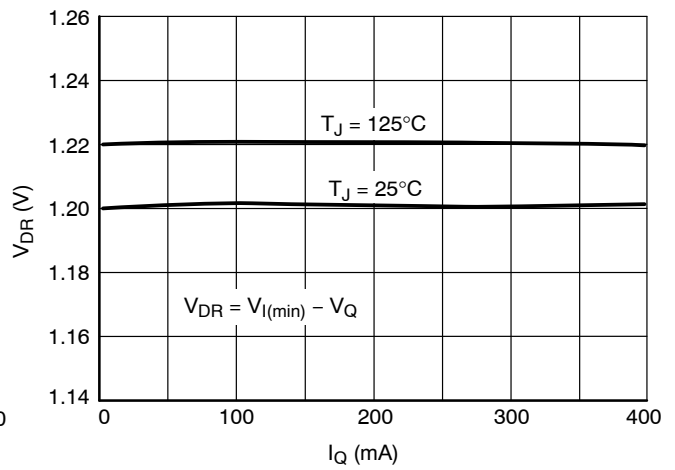


Figure 27. Voltage Drop vs. Output Current

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TYPICAL CHARACTERISTIC CURVES – 3.3 V Version

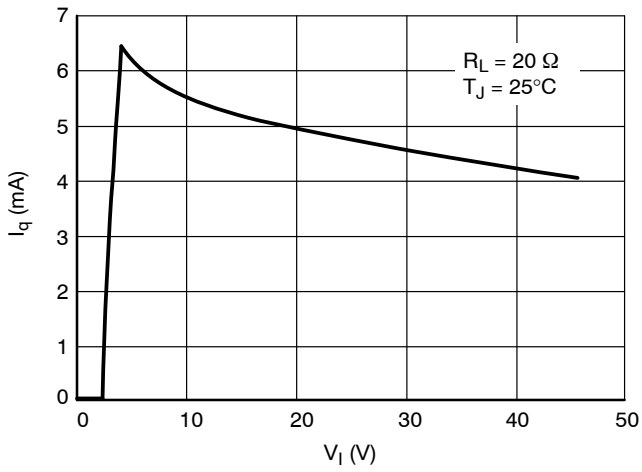


Figure 28. Current Consumption vs. Input Voltage

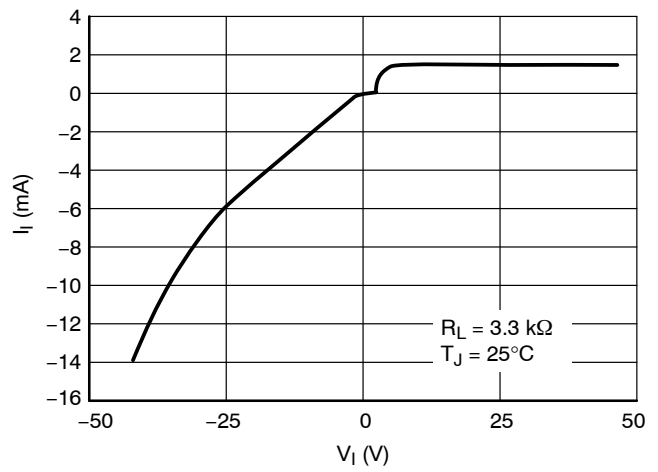


Figure 29. Input Current vs. Input Voltage

TYPICAL CHARACTERISTIC CURVES – 2.5 V Version

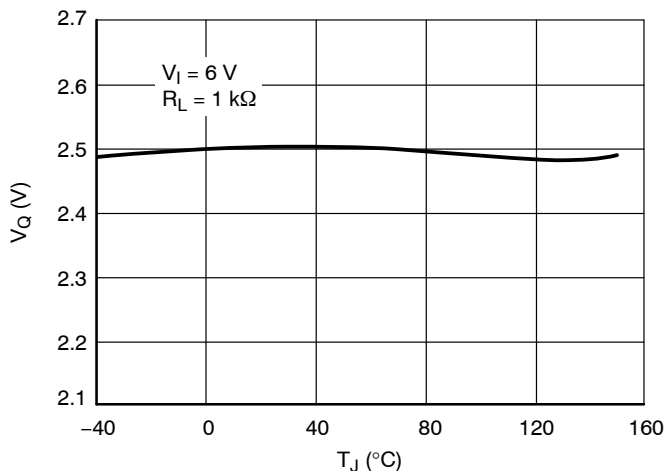


Figure 30. Output Voltage vs. Junction Temperature

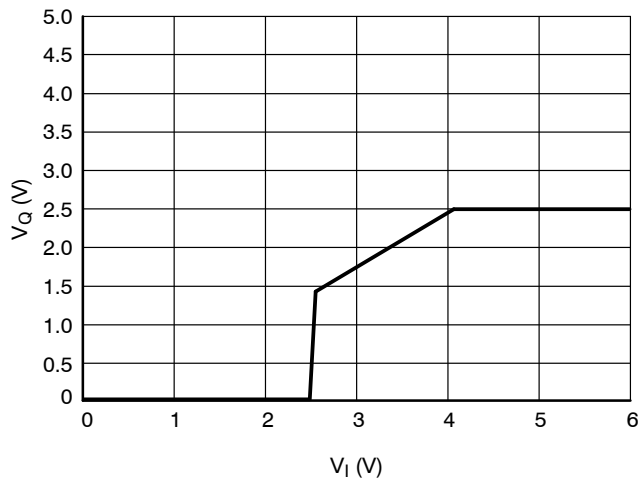


Figure 31. Output Voltage vs. Input Voltage

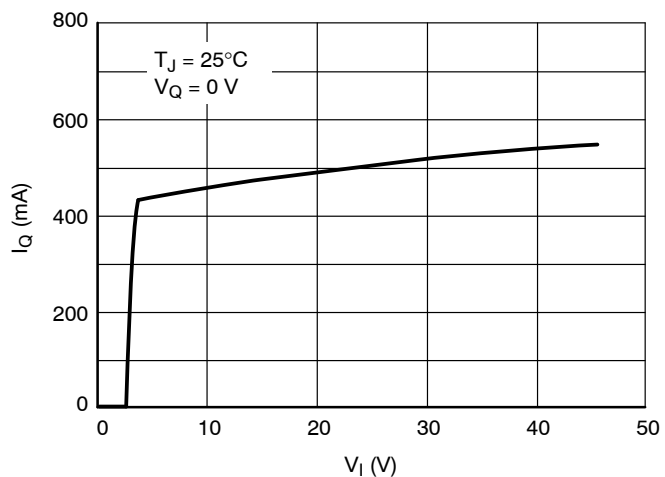


Figure 32. Output Current vs. Input Voltage

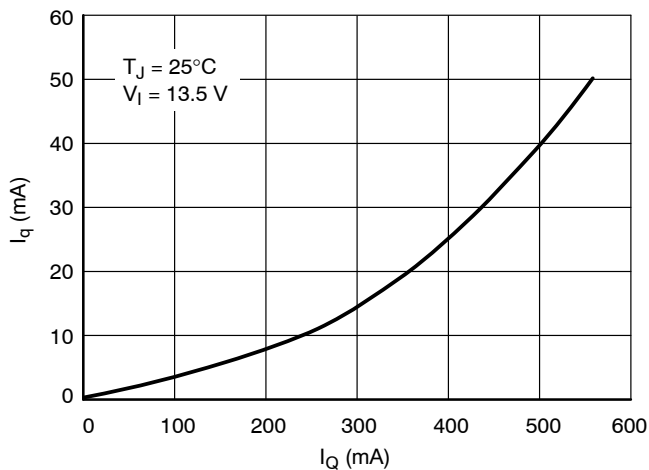


Figure 33. Current Consumption vs. Output Current (High Load)

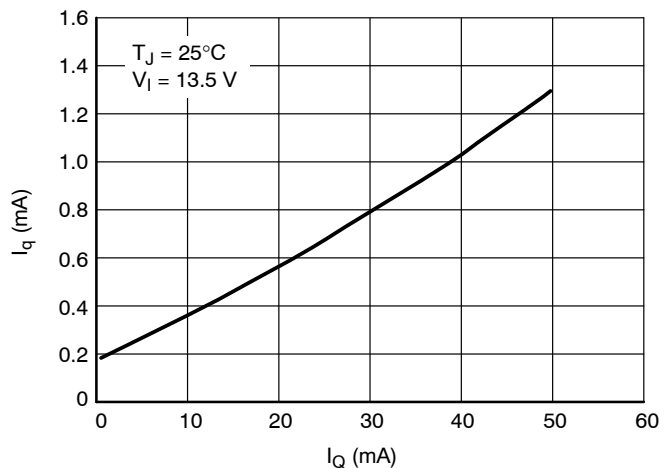


Figure 34. Current Consumption vs. Output Current (Low Load)

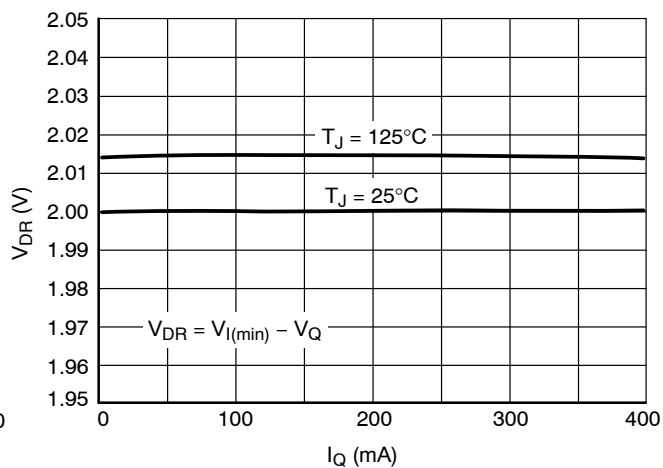


Figure 35. Voltage Drop vs. Output Current

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TYPICAL CHARACTERISTIC CURVES – 2.5 V Version

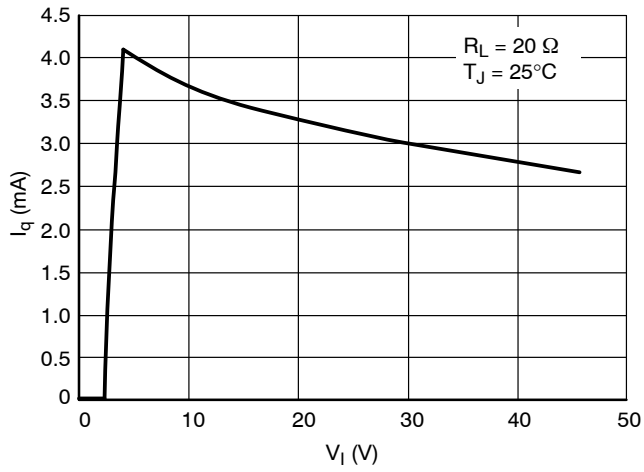


Figure 36. Current Consumption vs. Input Voltage

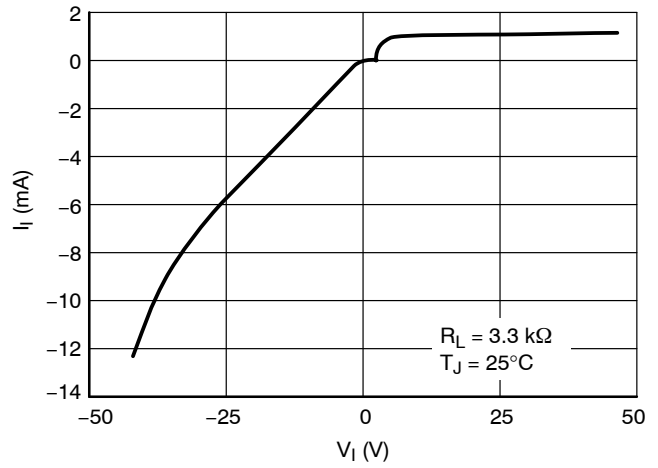


Figure 37. Input Current vs. Input Voltage

APPLICATION DESCRIPTION

Output Regulator

The output is controlled by a precision trimmed reference and error amplifier. The PNP output has saturation control for regulation while the input voltage is low, preventing over saturation. Current limit and voltage monitors complement the regulator design to give safe operating signals to the processor and control circuits.

Stability Considerations

The input capacitor C_{I1} in Figure 2 is necessary for compensating input line reactance. Possible oscillations caused by input inductance and input capacitance can be damped by using a resistor of approximately 1 Ω in series with C_{I2}.

The output or compensation capacitor helps determine three main characteristics of a linear regulator: startup delay, load transient response and loop stability.

The capacitor value and type should be based on cost, availability, size and temperature constraints. The aluminum electrolytic capacitor is the least expensive solution, but, if the circuit operates at low temperatures (–25°C to –40°C), both the value and ESR of the capacitor will vary considerably. The capacitor manufacturer’s data sheet usually provides this information.

The value for the output capacitor C_O shown in Figure 2 should work for most applications; however, it is not necessarily the optimized solution. Stability is guaranteed at values C_O ≥ 2.2 μF and an ESR ≤ 2.5 Ω within the operating temperature range. Actual limits are shown in a graph in the Typical Performance Characteristics section.

Calculating Power Dissipation in a Single Output Linear Regulator

The maximum power dissipation for a single output regulator (Figure 3) is:

$$P_{D(max)} = [V_{I(max)} - V_{Q(min)}]I_{Q(max)} + V_{I(max)}I_q \quad (eq. 1)$$

Where:

- V_{I(max)} is the maximum input voltage,
- V_{Q(min)} is the minimum output voltage,
- I_{Q(max)} is the maximum output current for the application, and
- I_q is the quiescent current the regulator consumes at I_{Q(max)}.

Once the value of P_{D(max)} is known, the maximum permissible value of R_{θJA} can be calculated:

$$P_{\theta JA} = \frac{(150 C - T_A)}{P_D} \quad (eq. 2)$$

The value of R_{θJA} can then be compared with those in the package section of the data sheet. Those packages with R_{θJA}’s less than the calculated value in Equation 2 will keep the die temperature below 150°C. In some cases, none of the packages will be sufficient to dissipate the heat generated by the IC, and an external heat sink will be required. The current flow and voltages are shown in the Measurement Circuit Diagram.

Heat Sinks

A heat sink effectively increases the surface area of the package to improve the flow of heat away from the IC and into the surrounding air.

Each material in the heat flow path between the IC and the outside environment will have a thermal resistance. Like series electrical resistances, these resistances are summed to determine the value of R_{θJA}:

$$R_{\theta JA} = R_{\theta JC} + R_{\theta CS} + R_{\theta SA} \quad (eq. 3)$$

Where:

- R_{θJC} = the junction–to–case thermal resistance,
 - R_{θCS} = the case–to–heat sink thermal resistance, and
 - R_{θSA} = the heat sink–to–ambient thermal resistance.
- R_{θJC} appears in the package section of the data sheet.

Like R_{θJA}, it too is a function of package type. R_{θCS} and R_{θSA} are functions of the package type, heat sink and the interface between them. These values appear in data sheets of heat sink manufacturers. Thermal, mounting, and heat sinking are discussed in the ON Semiconductor application note AN1040/D, available on the ON Semiconductor Website.

NCV4274, NCV4274A

ORDERING INFORMATION4

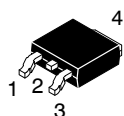
| Device* | Output Voltage Accuracy | Output Voltage | Package | Shipping† |
|-----------------|-------------------------|----------------|----------------------|--------------------|
| NCV4274ADS85R4G | 2% | 8.5 V | D2PAK (Pb-Free) | 800 / Tape & Reel |
| NCV4274DS50G | 4% | 5.0 V | D2PAK (Pb-Free) | 50 Units / Rail |
| NCV4274DS50R4G | 4% | 5.0 V | D2PAK (Pb-Free) | 800 / Tape & Reel |
| NCV4274DT50RKG | 4% | 5.0 V | DPAK (Pb-Free) | 2500 / Tape & Reel |
| NCV4274ADS50G | 2% | 5.0 V | D2PAK (Pb-Free) | 50 Units / Rail |
| NCV4274ADS50R4G | 2% | 5.0 V | D2PAK (Pb-Free) | 800 / Tape & Reel |
| NCV4274ADT50RKG | 2% | 5.0 V | DPAK (Pb-Free) | 2500 / Tape & Reel |
| NCV4274ST33T3G | 4% | 3.3 V | SOT-223 (Pb-Free) | 4000 / Tape & Reel |
| NCV4274DT33RKG | 4% | 3.3 V | DPAK (Pb-Free) | 2500 / Tape & Reel |
| NCV4274AST33T3G | 2% | 3.3 V | SOT-223 (Pb-Free) | 4000 / Tape & Reel |
| NCV4274ADT33RKG | 2% | 3.3 V | DPAK (Pb-Free) | 2500 / Tape & Reel |
| NCV4274ADS33R4G | 2% | 3.3 V | D2PAK (Pb-Free) | 800 / Tape & Reel |
| NCV4274ST25T3G | 4% | 2.5 V | SOT-223 (Pb-Free) | 4000 / Tape & Reel |
| NCV4274AST25T3G | 2% | 2.5 V | SOT-223 (Pb-Free) | 4000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

MECHANICAL CASE OUTLINE

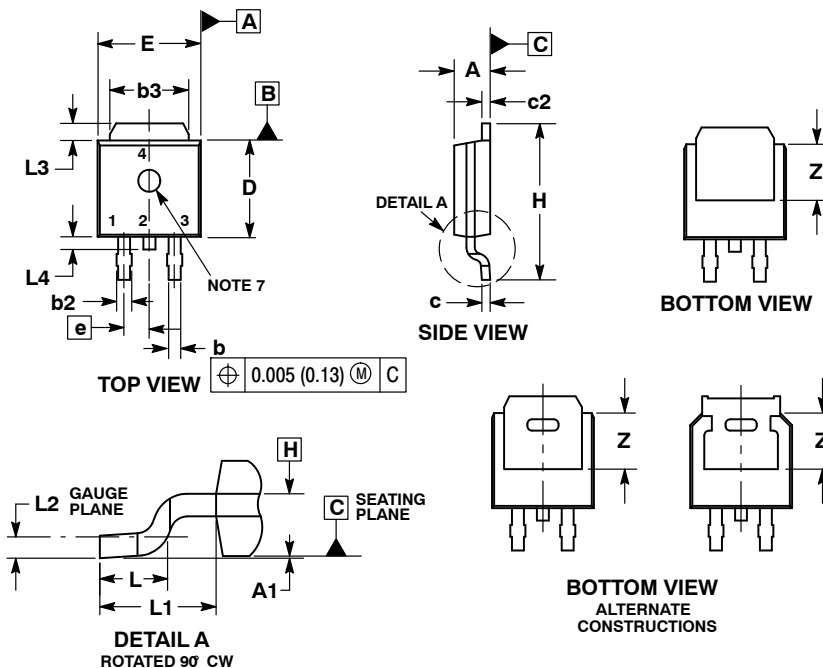
PACKAGE DIMENSIONS



DPAK (SINGLE GAUGE) CASE 369C ISSUE F

DATE 21 JUL 2015

SCALE 1:1



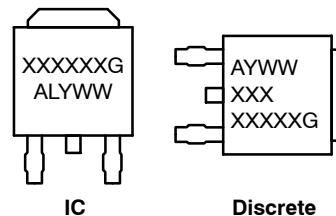
NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: INCHES.
- THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
- DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
- OPTIONAL MOLD FEATURE.

| DIM | INCHES | | MILLIMETERS | |
|-----|--------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.086 | 0.094 | 2.18 | 2.38 |
| A1 | 0.000 | 0.005 | 0.00 | 0.13 |
| b | 0.025 | 0.035 | 0.63 | 0.89 |
| b2 | 0.028 | 0.045 | 0.72 | 1.14 |
| b3 | 0.180 | 0.215 | 4.57 | 5.46 |
| c | 0.018 | 0.024 | 0.46 | 0.61 |
| c2 | 0.018 | 0.024 | 0.46 | 0.61 |
| D | 0.235 | 0.245 | 5.97 | 6.22 |
| E | 0.250 | 0.265 | 6.35 | 6.73 |
| e | 0.090 | BSC | 2.29 | BSC |
| H | 0.370 | 0.410 | 9.40 | 10.41 |
| L | 0.055 | 0.070 | 1.40 | 1.78 |
| L1 | 0.114 | REF | 2.90 | REF |
| L2 | 0.020 | BSC | 0.51 | BSC |
| L3 | 0.035 | 0.050 | 0.89 | 1.27 |
| L4 | --- | 0.040 | --- | 1.01 |
| Z | 0.155 | --- | 3.93 | --- |

GENERIC MARKING DIAGRAM*

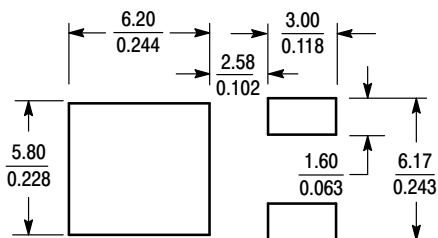
- | | | | | |
|--|--|---|---|--|
| <p>STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR</p> | <p>STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN</p> | <p>STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE</p> | <p>STYLE 4: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE</p> | <p>STYLE 5: PIN 1. GATE 2. ANODE 3. CATHODE 4. ANODE</p> |
| <p>STYLE 6: PIN 1. MT1 2. MT2 3. GATE 4. MT2</p> | <p>STYLE 7: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR</p> | <p>STYLE 8: PIN 1. N/C 2. CATHODE 3. ANODE 4. CATHODE</p> | <p>STYLE 9: PIN 1. ANODE 2. CATHODE 3. RESISTOR ADJUST 4. CATHODE</p> | <p>STYLE 10: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. ANODE</p> |



- XXXXXX = Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

SOLDERING FOOTPRINT*



SCALE 3:1 (mm/inches)

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

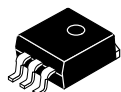
| | | |
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| DESCRIPTION: | DPAK (SINGLE GAUGE) | PAGE 1 OF 1 |

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MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

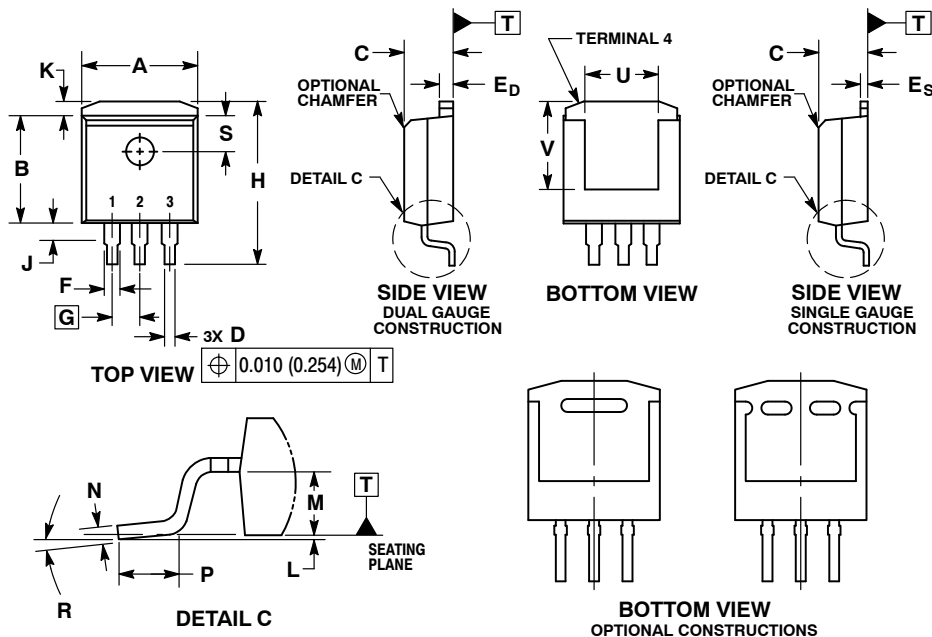
ON Semiconductor®



SCALE 1:1

D2PAK
CASE 418AF
ISSUE E

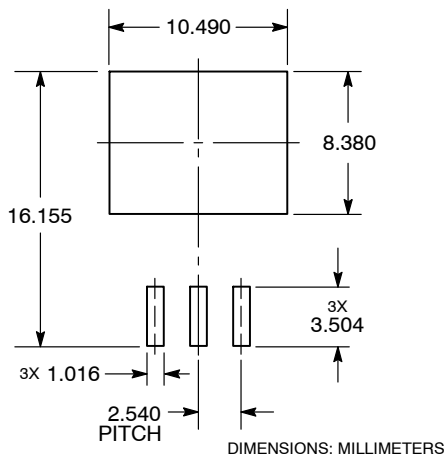
DATE 15 SEP 2015



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCHES.
 3. TAB CONTOUR OPTIONAL WITHIN DIMENSIONS A AND K.
 4. DIMENSIONS U AND V ESTABLISH A MINIMUM MOUNTING SURFACE FOR TERMINAL 4.
 5. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.025 (0.635) MAXIMUM.
 6. SINGLE GAUGE DESIGN WILL BE SHIPPED AFTER FPCN EXPIRATION IN OCTOBER 2011.

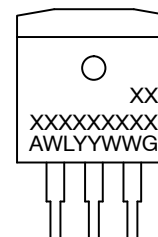
| DIM | INCHES | | MILLIMETERS | |
|----------------|-----------|-------|-------------|--------|
| | MIN | MAX | MIN | MAX |
| A | 0.386 | 0.403 | 9.804 | 10.236 |
| B | 0.356 | 0.368 | 9.042 | 9.347 |
| C | 0.170 | 0.180 | 4.318 | 4.572 |
| D | 0.026 | 0.036 | 0.660 | 0.914 |
| E _D | 0.045 | 0.055 | 1.143 | 1.397 |
| E _S | 0.018 | 0.026 | 0.457 | 0.660 |
| F | 0.051 REF | | 1.295 REF | |
| G | 0.100 BSC | | 2.540 BSC | |
| H | 0.539 | 0.579 | 13.691 | 14.707 |
| J | 0.125 MAX | | 3.175 MAX | |
| K | 0.050 REF | | 1.270 REF | |
| L | 0.000 | 0.010 | 0.000 | 0.254 |
| M | 0.088 | 0.102 | 2.235 | 2.591 |
| N | 0.018 | 0.026 | 0.457 | 0.660 |
| P | 0.058 | 0.078 | 1.473 | 1.981 |
| R | 0° | 8° | 0° | 8° |
| S | 0.116 REF | | 2.946 REF | |
| U | 0.200 MIN | | 5.080 MIN | |
| V | 0.250 MIN | | 6.350 MIN | |

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

| | | |
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| DESCRIPTION: | D2PAK | PAGE 1 OF 1 |

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